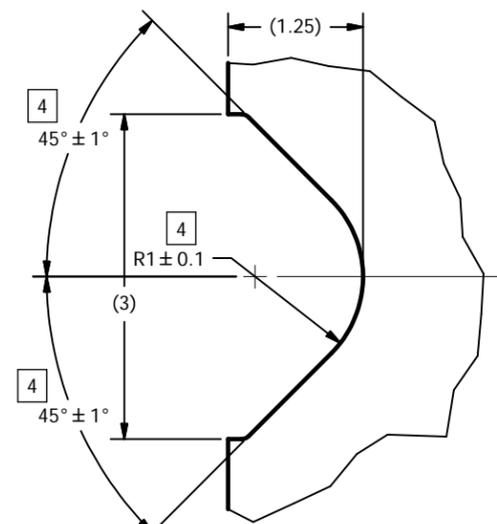


NOTES UNLESS OTHERWISE SPECIFIED:

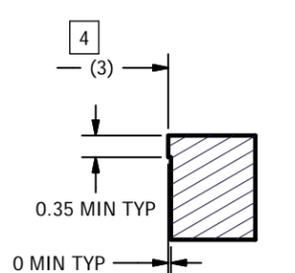
- 1 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
- 2 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.6 DEGREES.
- 3 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE ARRAY.
- 4 NOTCH DIMENSIONS ARE DEFINED BY UPPERMOST LAYERS OF CERAMIC, AS SHOWN IN SECTION A-A.
- 5 ENCAPSULANT TO BE CONTAINED WITHIN DIMENSIONS SHOWN IN VIEW D (SHEET 3). NO ENCAPSULANT IS ALLOWED ON TOP OF THE WINDOW.
- 6 ENCAPSULANT NOT TO EXCEED THE HEIGHT OF THE WINDOW.
- 7 SEE DETAIL B FOR "V-NOTCH" DIMENSIONS.
- 8 WHILE ONLY THE THREE DATUM A TARGET AREAS A1, A2, AND A3 ARE USED FOR MEASUREMENT, ALL 4 CORNERS SHOULD BE CONTACTED, INCLUDING E1, TO SUPPORT MECHANICAL LOADS.

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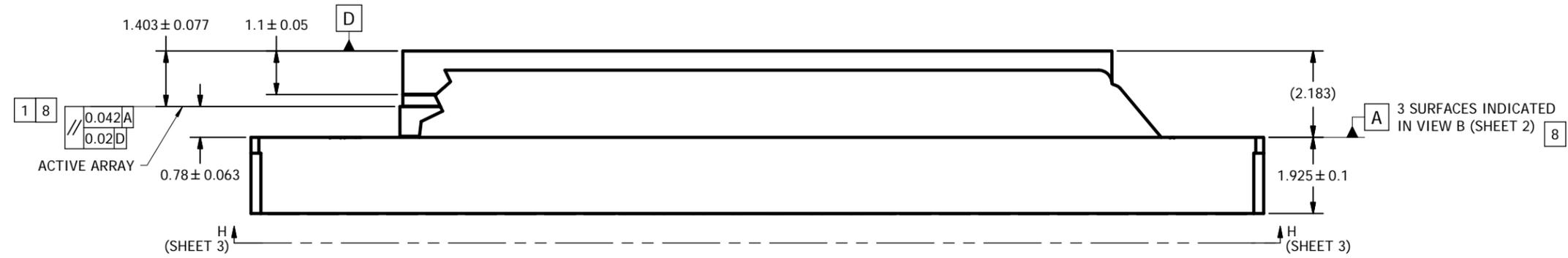
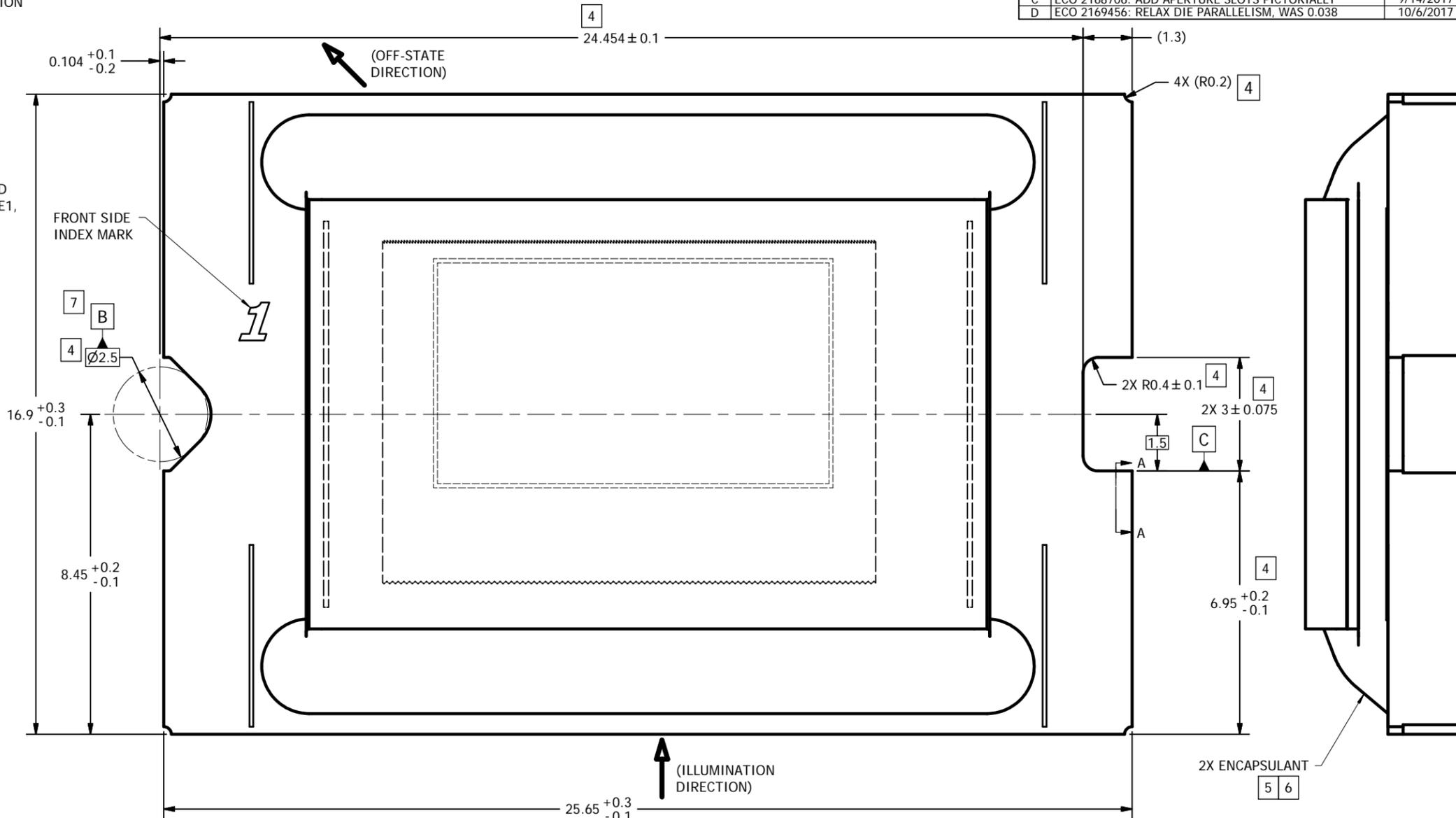
REVISIONS			
REV	DESCRIPTION	DATE	BY
A	ECO 2162276: INITIAL RELEASE	11/14/2016	BMH
B	ECO 2167828: CORRECT BACK SIDE MARKING; WAS 227-X	7/24/2017	BMH
C	ECO 2168706: ADD APERTURE SLOTS PICTORIALY	9/14/2017	BMH
D	ECO 2169456: RELAX DIE PARALLELISM, WAS 0.038	10/6/2017	BMH



DETAIL B
V-NOTCH
SCALE 30 : 1



SECTION A-A
(ROTATED 90°)



THIRD ANGLE PROJECTION

0314DA	APPLICATION
NEXT ASSY	USED ON

UNLESS OTHERWISE SPECIFIED
 ● DIMENSIONS ARE IN MILLIMETERS
 ● TOLERANCES:
 ANGLES ± 1°
 2 PLACE DECIMALS ± 0.25
 1 PLACE DECIMALS ± 0.50
 ● DIMENSIONAL LIMITS APPLY BEFORE PROCEEDING
 ● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994
 ● REMOVE ALL BURRS AND SHARP EDGES
 ● PARENTHETICAL INFORMATION FOR REFERENCE ONLY

DRAWN	DATE
B. HASKETT	11/14/2016
ENGINEER	
B. HASKETT	11/14/2016
QA/CE	
P. KONRAD	11/14/2016
CM	
S. SUSI	11/15/2016
APPROVED	
M. DORAK	11/17/2016
R. LONG	11/16/2016

TITLE ICD, MECHANICAL, DMD, .47 4K SERIES 316 (FQN PACKAGE)	
SIZE	D
DWG NO	2515301
SCALE	15:1
REV	D
SHEET 1 OF 5	

D

D

C

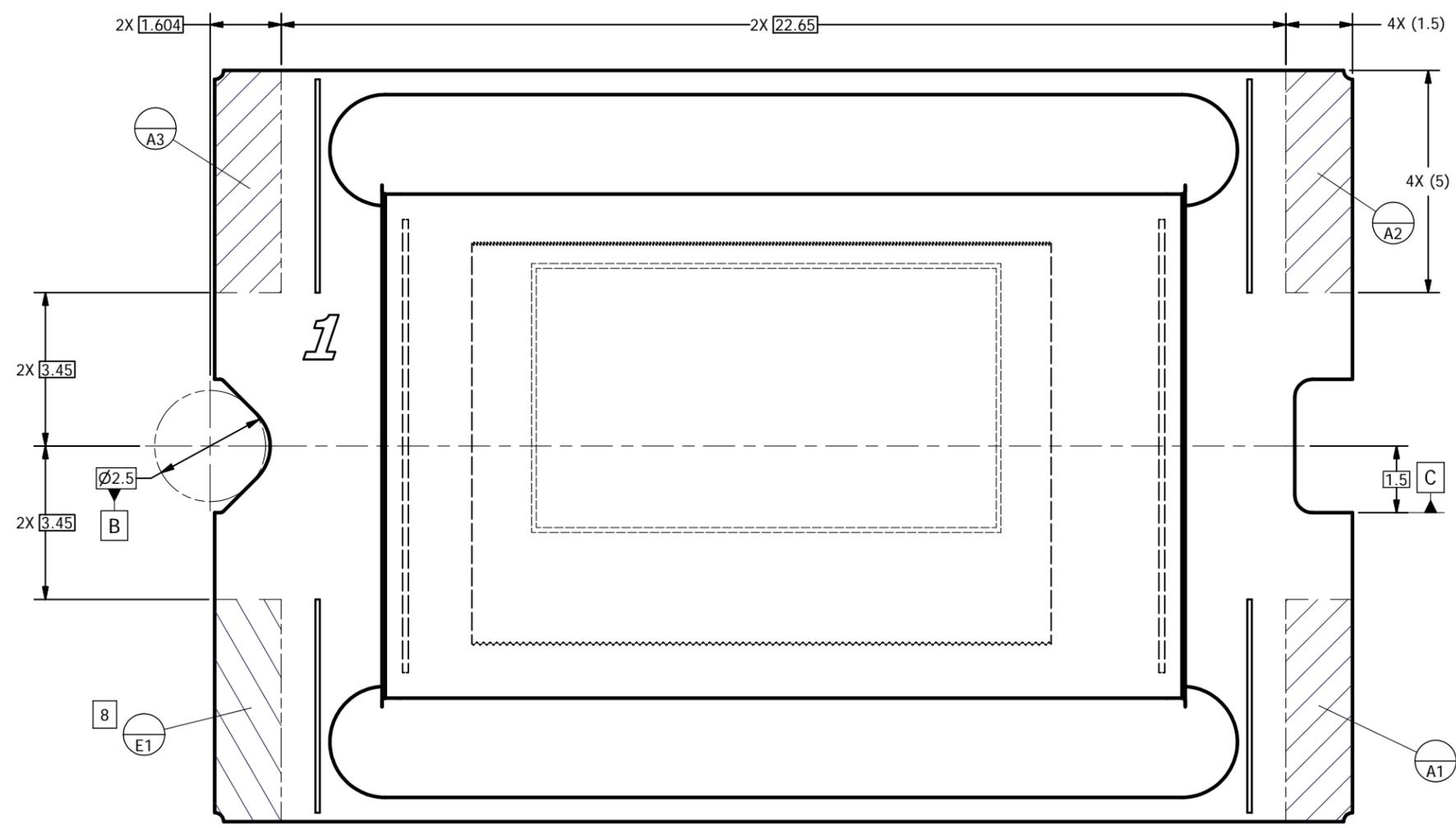
C

B

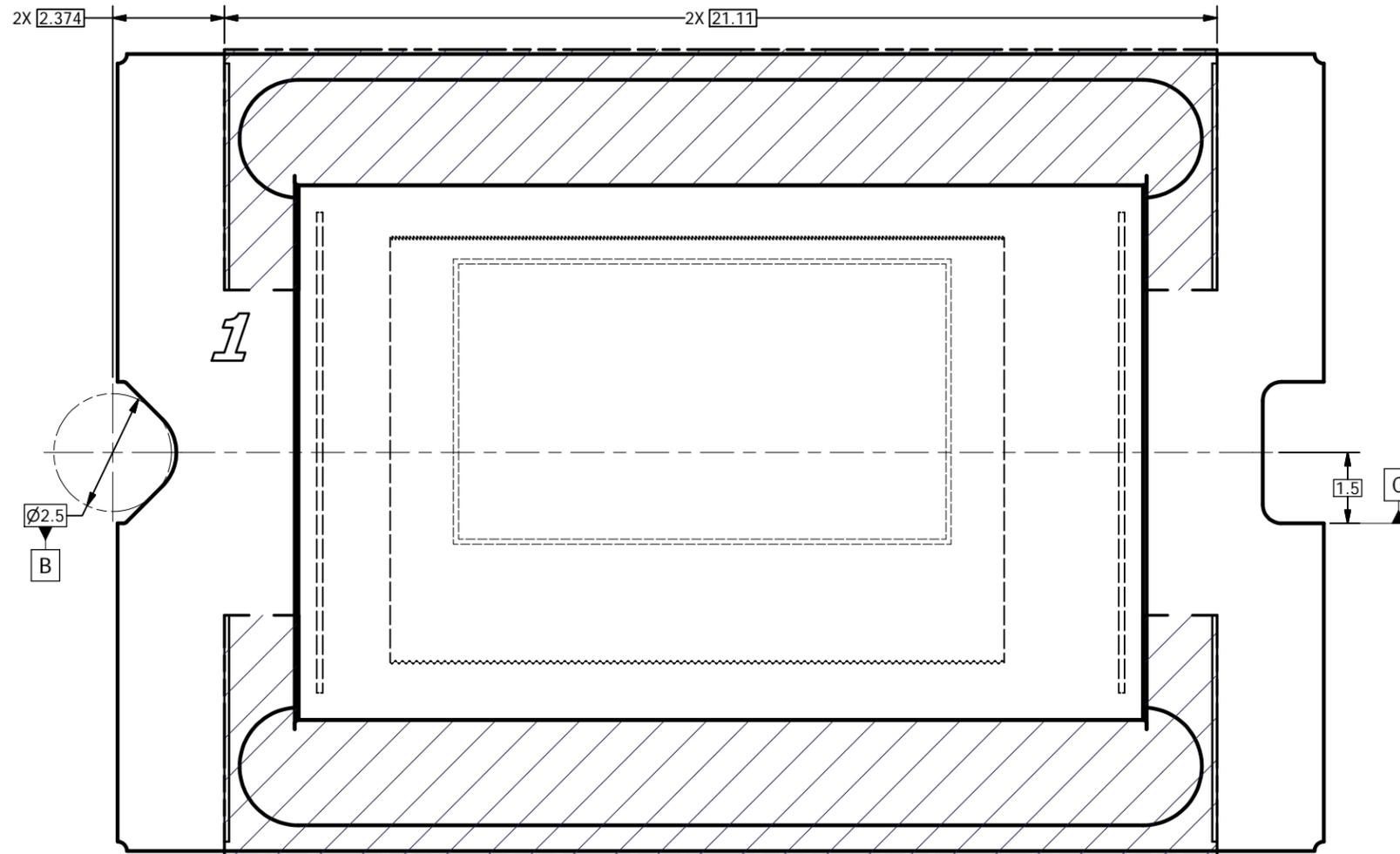
B

A

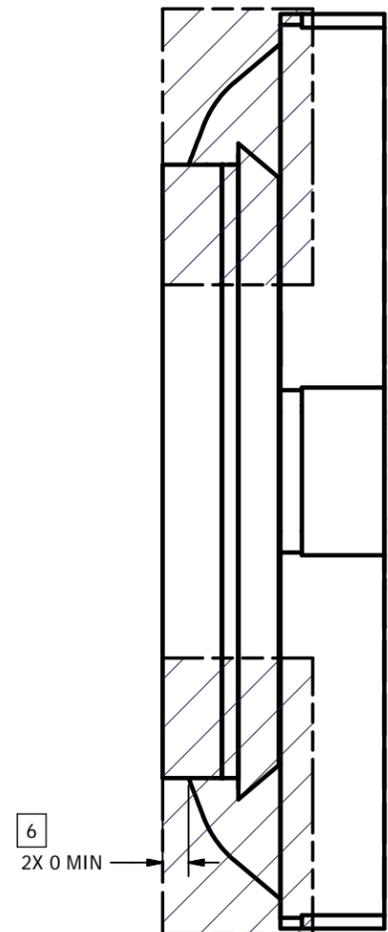
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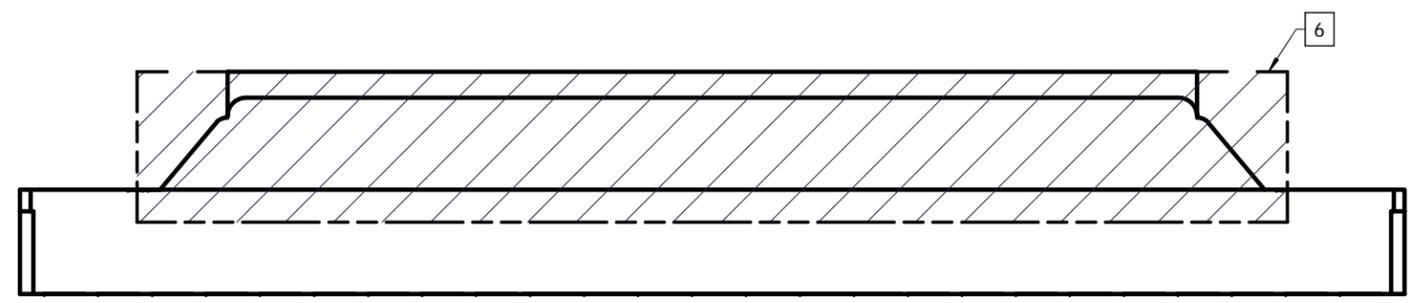
VIEW C
 DATUMS A AND E
 (FROM SHEET 1)



VIEW D
ENCAPSULANT MAXIMUM X/Y DIMENSIONS [5]
(FROM SHEET 1)



VIEW E
MAXIMUM ENCAPSULANT HEIGHT



D

D

C

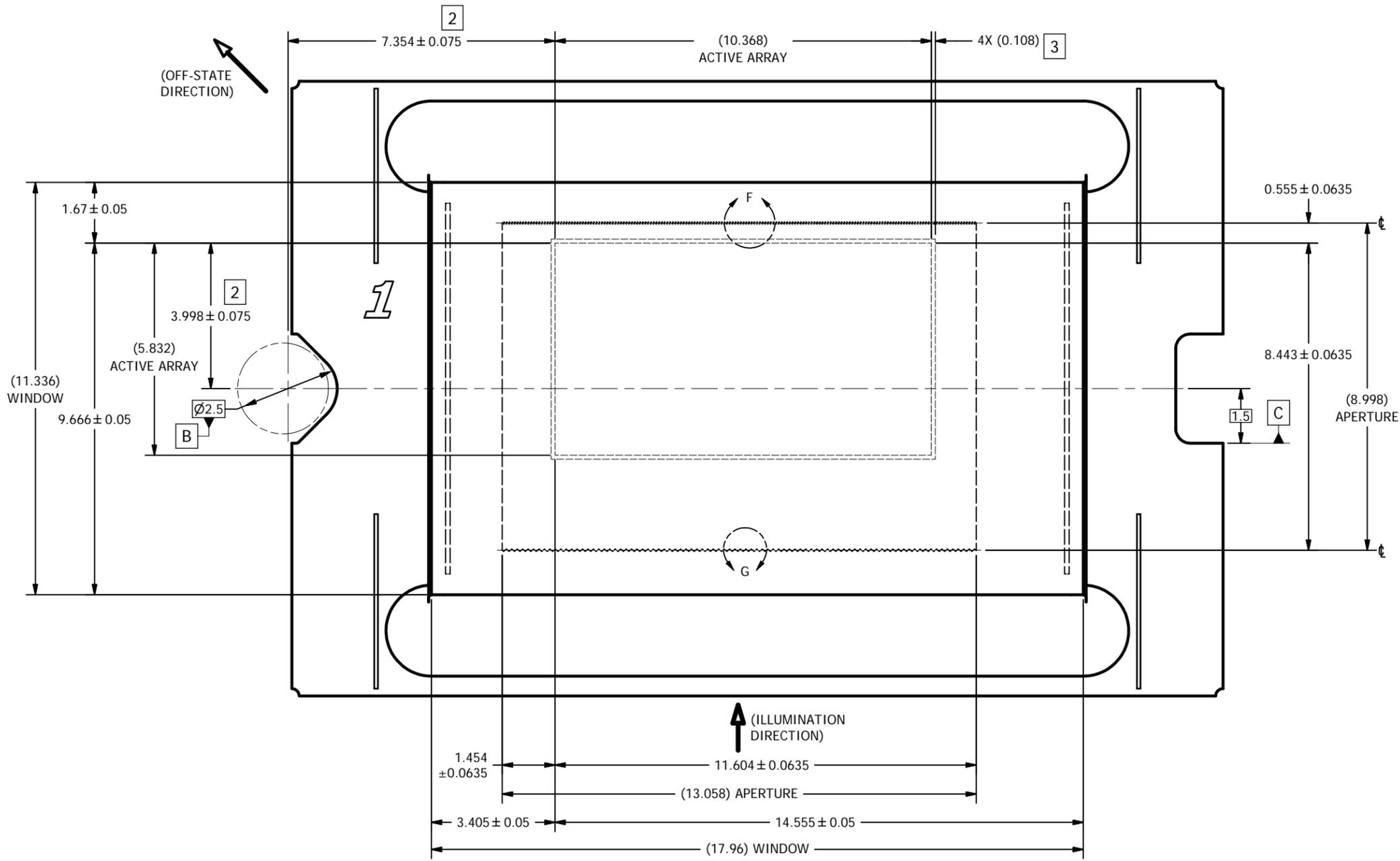
C

B

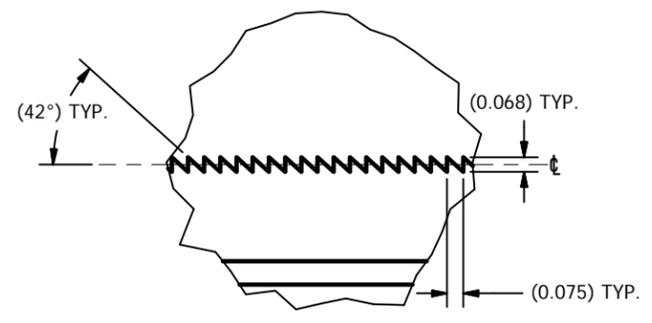
B

A

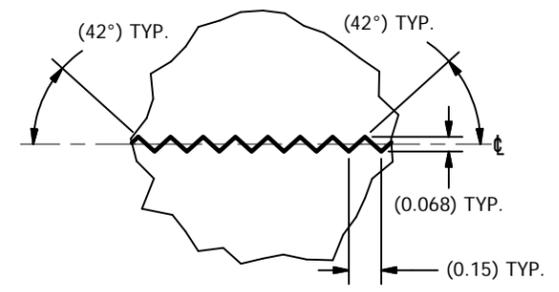
A



VIEW E
WINDOW AND ACTIVE ARRAY
 (FROM SHEET 1)



DETAIL F
APERTURE TOP EDGE
 SCALE 60 : 1



DETAIL G
APERTURE BOTTOM EDGE
 SCALE 60 : 1

D

D

C

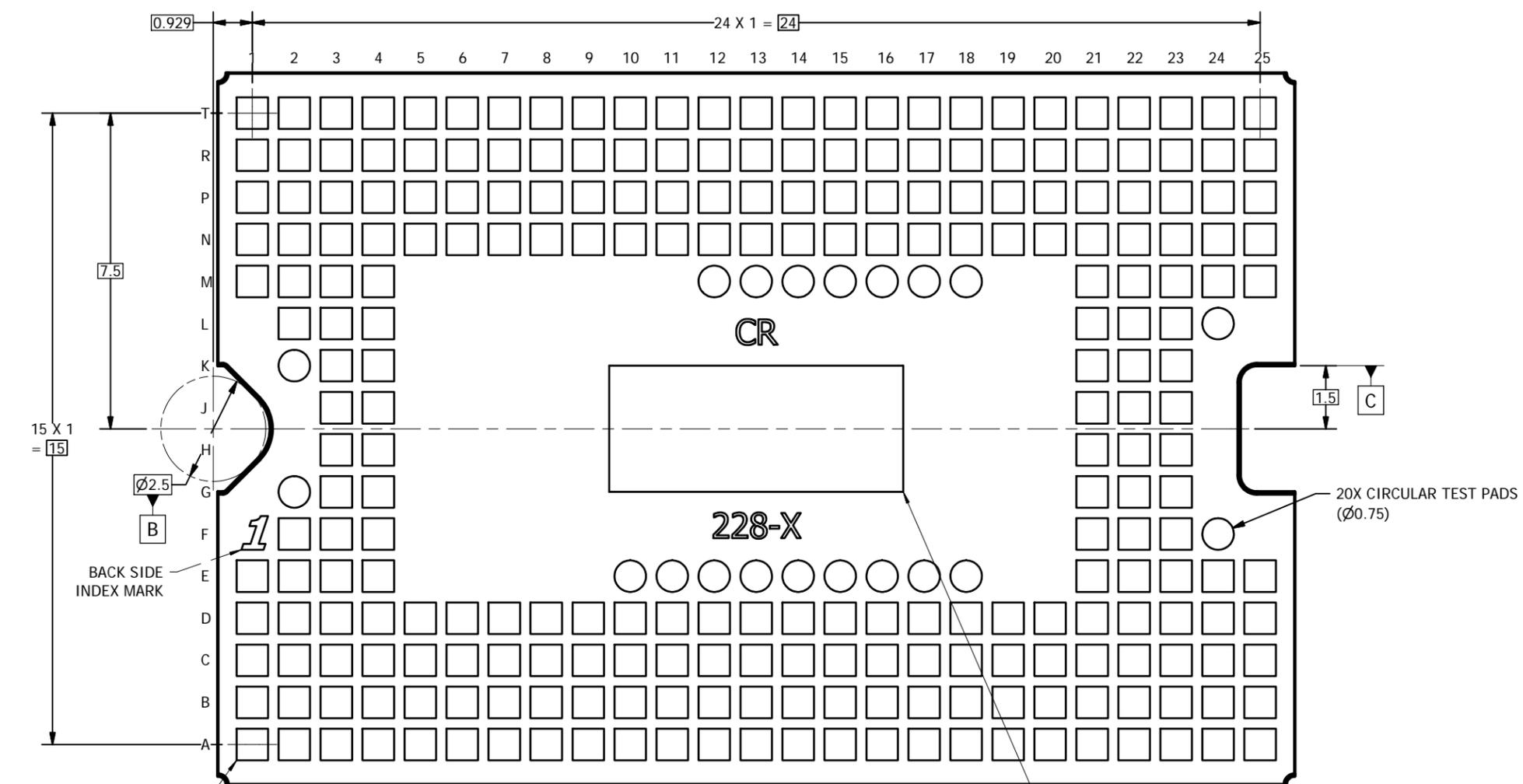
C

B

B

A

A



250X SQUARE LGA PADS
 0.75±0.05 X 0.75±0.05

0.2A BC
0.1A

VIEW H-H
 BACK SIDE METALLIZATION
 (FROM SHEET 1)

SYMBOLIZATION PAD
 (7 X 3)

20X CIRCULAR TEST PADS
 (Ø0.75)

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